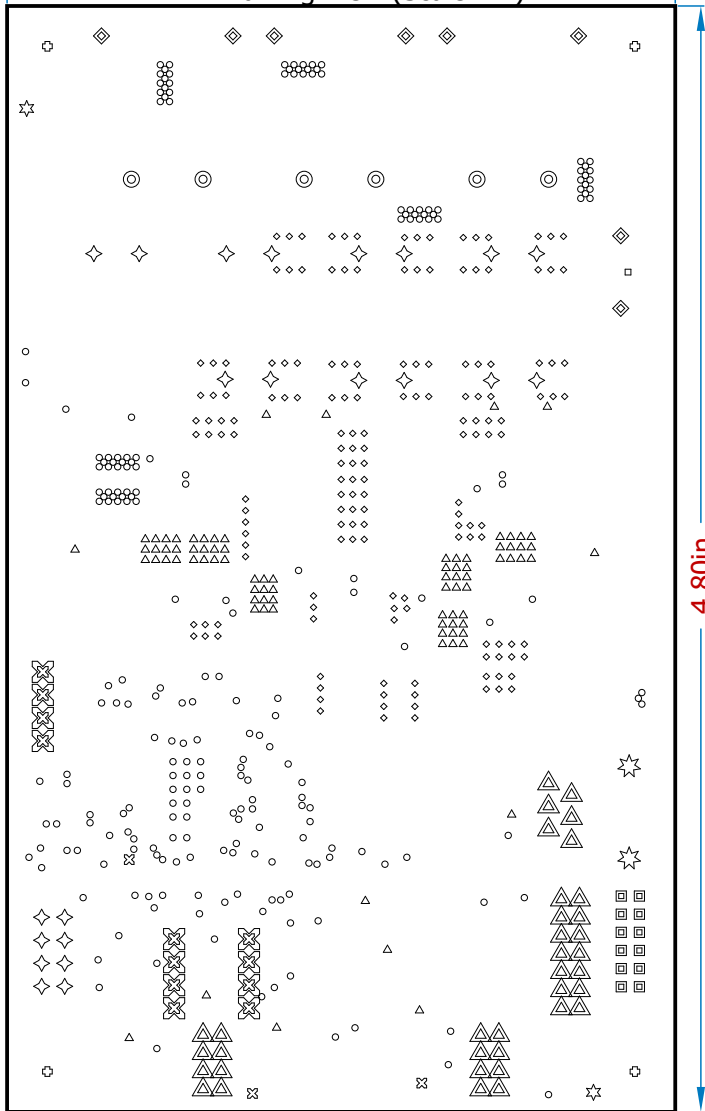




## PRODUCTION DEMO BOARD FABRICATION NOTES: (Unless Otherwise Specified):

1. PCB Part Number: 600-DC2703\_REV04
2. FAB STANDARD: IPC-A-600 CLASS 2
3. MATERIAL: EPOXY FIBERGLASS, ISOLA 370HR; 6 LAYERS WITH 2 OZ. Cu OUTER / 1OZ INNER; FINISHED THICKNESS TO BE 0.062" +/- .010"; FLAMMABILITY RATING: 94 V-O MINIMUM.
4. SIZE: SINGULATED; BOARD OUTLINE LAYER IS THE EDGE OF THE PCB, NOT THE ROUTER PATH; 0.00" ARE PRIMARY DATUMS; DEBURR AND BREAK ALL SHARP EDGES.
5. DRILLING: PER SCHEDULE, FORMAT 2/5 NO SUPPRESSION; ALL HOLE SIZES ARE SPECIFIED AFTER PLATING; HOLE LOCATION TOLERANCES ARE +/-0.003" IN RELATION TO CENTER; NO VIA FILL FOR VIA-IN-PAD.
6. FINISH: ENiG
7. SOLDERMASK: SMOBC, LPI BOTH SIDES, COLOR BLACK.
8. SILKSCREENS: LPI BOTH SIDES, WHITE NON-CONDUCTIVE INK
9. DATA WHICH MAY NOT BE MODIFIED WITHOUT WRITTEN APPROVAL: SOLDER MASK LAYERS-REJECT DESIGN FOR WIDTH VIOLATIONS; SILKSCREEN OVER EXPOSED COPPER
10. DATA WHICH MAY BE MODIFIED WITH REPORTING UPDATED GERBER DATA: NONFUNCTIONAL PADS MAY BE REMOVED, PAD TEARDROPPING MAY BE ADDED
11. DATA WHICH MAY BE MODIFIED WITHOUT REPORTING: COPPER FEATURES MAY ADJUST TO COMPENSATE FOR ETCHING PROCESSES
12. IPC NETLIST COMPARE BEFORE FABRICATION: DC2703\_PCB-Rev4.cvg is IPC-2581B with Merged Nets for Kelvin Net-Ties
13. NO STAMPS OR MARKS FOR QA, TEST, DATE CODE, MANUFACTURER, ETC ON ANY BOARD NOT MARKED 'SOLDER SAMPLE'

2.90in  
Drill Drawing View (Scale 1.2)



4.80in

Drill Table

Symbol	Count	Hole Size	Plated	Via / Pad	Hole Tolerance
○	228	10mil	Plated	Via	+/-3mil
⊗	3	15mil	Plated	Pad	+/-3mil
△	85	15mil	Plated	Via	+/-3mil
◇	160	20mil	Plated	Via	+/-3mil
◻	12	31mil	Plated	Pad	+/-3mil
▲	36	35mil	Plated	Pad	+/-3mil
⊗	12	39mil	Plated	Pad	+/-3mil
◇	22	43mil	Plated	Pad	+/-3mil
◇	8	59mil	Plated	Pad	+/-3mil
☆	2	70mil	Non-Plated	Pad	+/-3mil
◎	6	71mil	Plated	Pad	+/-3mil
◻	1	106mil	Non-Plated	Pad	+/-3mil
⊕	4	125mil	Plated	Pad	+/-3mil
☆	2	130mil	Non-Plated	Pad	+/-3mil
	581 Total				